PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT2672450

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
BO-JIUN LIN	12/16/2013
HSIN-CHIEH YAO	12/16/2013
HAI-CHING CHEN	12/18/2013
TIEN-I BAO	12/18/2013

RECEIVING PARTY DATA

Name:	Taiwan Semiconductor Manufacturing Company, Ltd.
Street Address:	No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park
City:	Hsin-Chu
State/Country:	TAIWAN
Postal Code:	300-77

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	14138743

CORRESPONDENCE DATA

Fax Number: (214)200-0853
Phone: 972-739-8635
Email: ipdocketing@haynesboone.com
Correspondence will be sent via US Mail when the email attempt is unsuccessful.
Correspondent Name: HAYNES AND BOONE, LLP IP SECTION
Address Line 1: 2323 VICTORY AVENUE
Address Line 2: SUITE 700
Address Line 4: DALLAS, TEXAS 75219

ATTORNEY DOCKET NUMBER:	24061.2663
NAME OF SUBMITTER:	LINDA INGRAM

Signature:	/Linda Ingram/
Date:	01/08/2014
Total Attachments: 3 source=2663_Assignment#page1.tif source=2663_Assignment#page2.tif source=2663_Assignment#page3.tif	

Docket No.: 2013-1151/24061.2663
Customer No.: 000042717

ASSIGNMENT

WHEREAS, we,

(1) Bo-Jiun Lin of 9F., No.68-2, Jhuangjing 5th Street, Jhubei City, Hsinchu County 30264 Taiwan R.O.C.

(2) Hsin-Chieh Yao of 12F., No.179, Guanxin N. Road, East District, Hsinchu City 300, Taiwan R.O.C.

(3) Hai-Ching Chen of 15F.-5, No.37, Jianzhong 1st Road, Hsinchu City

(4) Tien-I Bao of 6F., No.366, Sec. 4, Linghang N. Road, Dayuan Township, Taoyuan County 337, Taiwan R.O.C.

have invented certain improvements in

SYSTEM AND METHOD FOR DARK FIELD INSPECTION

for which we have executed an application for Letters Patent of the United States of America,

_______ of even date filed herewith; and
__X__ filed on December 23, 2013, and assigned application number 14/138,743; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Bo-Jiun Lin

Residence Address: 9F., No.68-2, Jhuangjing 5th Street, Jhubei City
Hsinchu County 30264 Taiwan R.O.C.

✓Dated: 2013.12.16

✓ 林伯俊 / Bo-Jiun Lin
Inventor Signature

Inventor Name: Hsin-Chieh Yao

Residence Address: 12F., No.179, Guanxin N. Road, East District
Hsinchu City 300, Taiwan R.O.C.

✓Dated: 2013/12/16

✓ Hsin-Chieh Yao
Inventor Signature

Inventor Name: Hai-Ching Chen

Residence Address: 15F.-5, No.37, Jianzhong 1st Rd., Hsinchu City

✓Dated: 2013/12/18

✓ Hai Ching Chen
Inventor Signature

Inventor Name: Tien-I Bao

Residence Address: 6F., No.366, Sec. 4, Linghang N. Road, Dayuan Township, Taoyuan County 337, Taiwan R.O.C.

✓ Dated: 12/18/2013

✓ Tien-I Bao
Inventor Signature
